JJMICROELECTRONICS

80V, 206A, 2.7mΩ N-channel Power SGT MOSFET

JMSH0803ME

Features

- Excellent $R_{\text{DS(ON)}}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

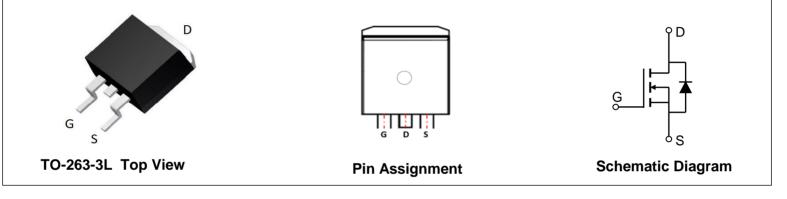
- Load Switch
- PWM Application
- Power Management

Parameters	Value	Unit
V _{DSS}	80	V
V _{GS(th)_Typ}	3.0	V
I _D (@V _{GS} =10V)	206	А
R _{DS(ON)_Typ} (@V _{GS} =10V	2.7	mΩ



Product Summary





Ordering Information

Device	Marking	MSL Form Package		Package	Reel(pcs)	Per Carton (pcs)
JMSH0803ME	JMSH0803ME	3	Tape&Reel	TO-263-3L	800	4000

Absolute Maximum Ratings (@ $T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Unit	
V _{DS}	Drain-to-Source Voltage		80	V	
V_{GS}	Gate-to-Source Voltage		±20	V	
1-	Continuous Drain Current	$T_C = 25^{\circ}C$	206	A	
Ι _D		$T_{\rm C} = 100^{\circ}{\rm C}$	146	A	
I _{DM}	Pulsed Drain Current (1)		Refer to Fig.4	А	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾		900	mJ	
P _D	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	268	W	
' D	Fower Dissipation	$T_{\rm C} = 100^{\circ}{\rm C}$	107		
T _J , T _{STG}	Junction & Storage Temperature Range		-55 to 150	°C	

Thermal Characteristics

Symbol	Parameter	Мах	Unit	
R _{0JA}	Thermal Resistance, Junction to Ambient ⁽³⁾	34	°C/W	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.47	-0/00	

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					<u></u>
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_{D} = 250 \mu A, V_{GS} = 0V$	80	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 64V, V_{GS} = 0V$	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics	•		•	•	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.1	3.0	4.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_{D} = 20A$	-	2.7	3.5	mΩ
Dynami	ic Characteristics			•		
R_g	Gate Resistance	f = 1MHz	-	0.8	-	Ω
C _{iss}	Input Capacitance		-	6396	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 40V,$ f = 1MHz	-	1224	-	pF
C _{rss}	Reverse Transfer Capacitance		-	23	-	pF
Q _g	Total Gate Charge		-	91	-	nC
Q _{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 40V, I_D = 20A$	-	33	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} = 40 V, I <u>D</u> = 20/V	-	18	-	nC
Switchi	ing Characteristics					
t _{d(on)}	Turn-On DelayTime		-	31	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10V, V _{DD} = 39V	-	35	-	ns
t _{d(off)}	Turn-Off DelayTime	$I_{\rm D}$ = 20A, $R_{\rm GEN}$ = 6.2 Ω	-	61	-	ns
t _f	Turn-Off Fall Time		-	31	-	ns
Body D	iode Characteristics			I		
I _S	Maximum Continuous Body Diode Forward Current		-	-	206	А
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	824	А
$V_{\rm SD}$	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time		-	75	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F = 20A, di/dt = 100A/us		155	-	nC

Electrical Characteristics ($T_J = 25^{\circ}C$ unless otherwise specified)

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

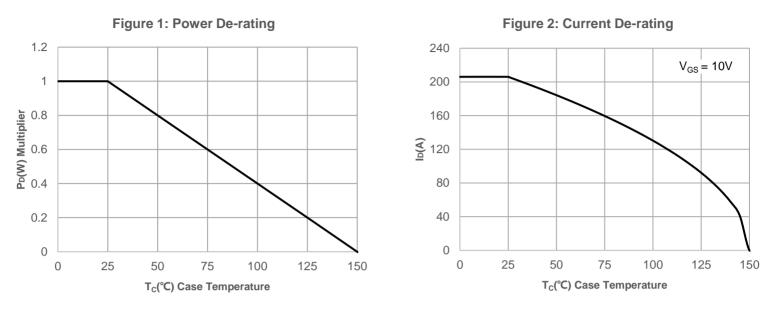
2. E_{AS} condition: Starting T_J =25C, V_{DD} =40V, V_G =10V, R_G =25ohm, L=3mH, I_{AS} =24.5A, V_{DD} =0V during time in avalanche.

3. $R_{\theta JA}$ is measured with the device mounted on a 1inch 2 pad of 2oz copper FR4 PCB.

4. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 0.5%.

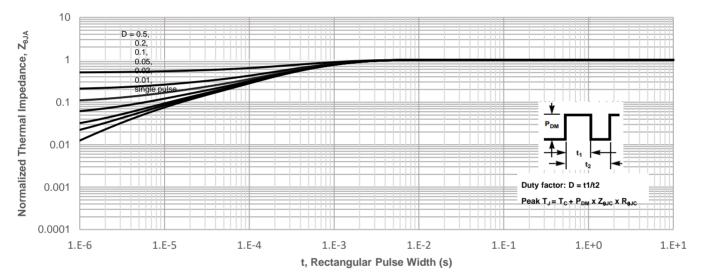




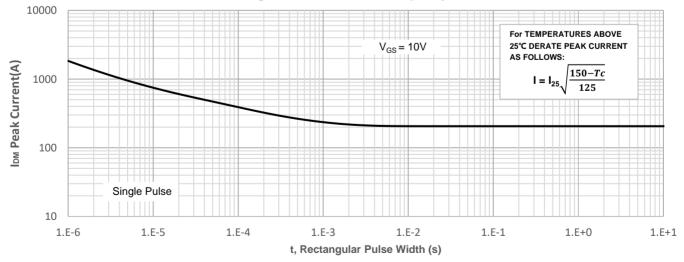


Typical Performance Characteristics









T_J = -55°C

 $T_J = 25^{\circ}C$

5.5

6

1.2

4.5

0.8

5

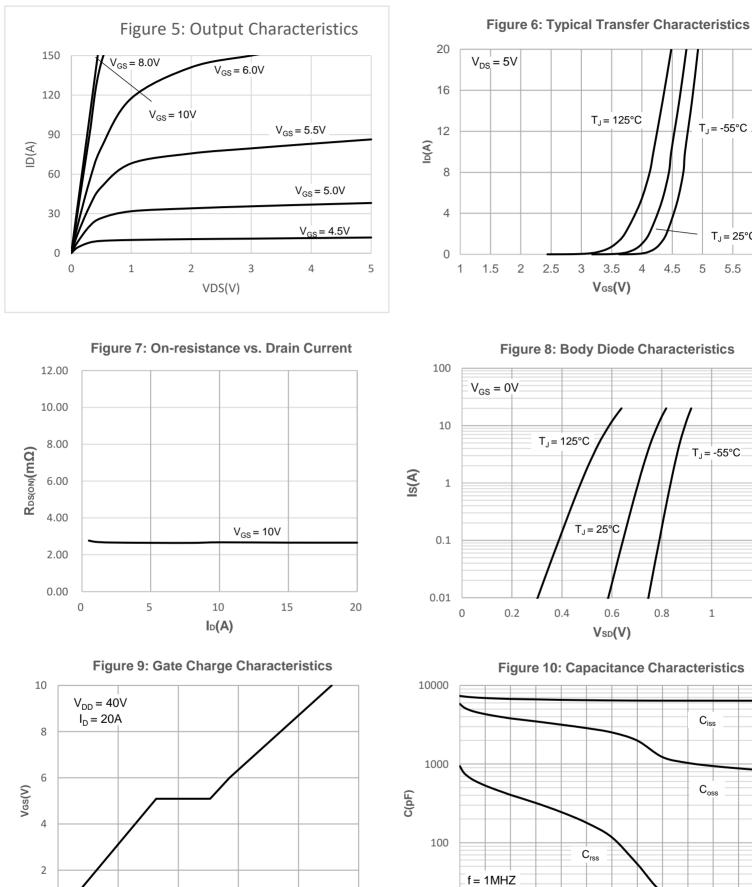
T_J=-55°C

1

Ciss

Coss

50 55 60



Typical Performance Characteristics

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Qg(nC)

60

40

20

0

0

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20 25 30 35 40 45

VDS(V)

 $V_{GS} = 0V$

10 15

10

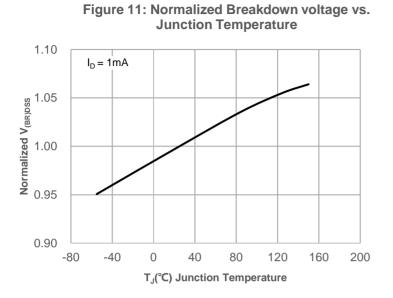
0 5

100

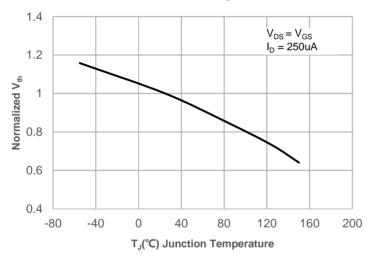
80

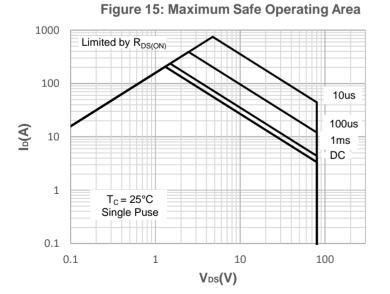


Typical Performance Characteristics









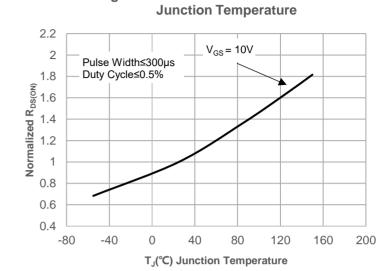
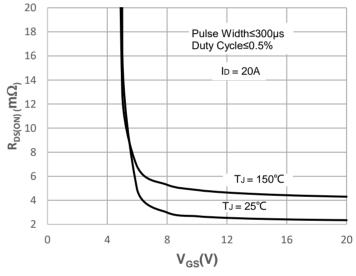


Figure 12: Normalized on Resistance vs.





Test Circuit

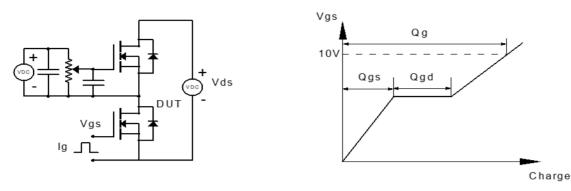


Figure 1: Gate Charge Test Circuit & Waveform

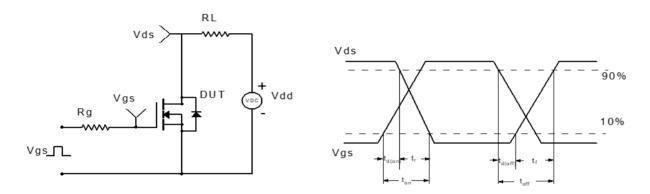


Figure 2: Resistive Switching Test Circuit & Waveform

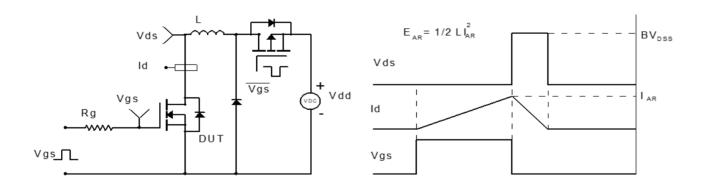


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

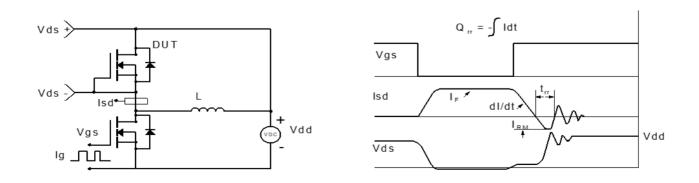


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-263-3L)

		Dimensions						
		Ref.	Millimeters		Inches			
			Min.	Тур.	Max.	Min.	Тур.	Max.
		А	9.90		10.20	0.390		0.402
		В	14.70		15.80	0.579		0.622
A	<u>M</u> _	С	9.4		9.6	0.37		0.378
		D		2.54			0.100	
		E	1.20		1.40	0.047		0.055
		F	0.75		0.85	0.029		0.033
		G			1.75			0.069
		н	4.40		4.70	0.173		0.185
	ſ	J	2.30		2.70	0.091		0.106
	<u> </u>	к	0.38		0.55	0.015		0.022
		L	0	0.10	0.25	0	0.004	0.010
TO-2	263	М	1.25		1.35	0.049		0.053

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